

# [CHIP PACKAGE STRUCTURE]

## Abstract

A chip package structure includes a substrate having an upper surface and a lower surface, a chip having an active surface and a back surface, a stiffener, a first heat sink and a second heat sink. The active surface of the chip is attached on the upper surface of the substrate via bumps, so that the chip electrically connects to the substrate. The stiffener is disposed on the upper surface of the substrate and around the chip. The first heat sink is disposed on the back surface of the chip and on the stiffener ring. The second heat sink is disposed on the lower surface of the substrate.